स्टीरियो के सिद्धांत:

SLA (Stereolithography) एक सामान्य रैपिडप्रोटोटाइपिंग तकनीक है, यह एक तरल फोटो को पोलीमराइज़ करने के लिए लेजर का उपयोग करता है तथा तकनीक जिसका परिणामप्रकाश को स्थानीयकृत करना स्थान (बिंदु / रेखा) पोलीमराइज़ की जाती है, जिससे आपको एक ठोस त्रिआयामी परत को एक बार-परतफोटोन बीम को मॉडलिंग की आवश्यकता के अनुसार के साथ स्थान इसका ठोस Photopolymers फोटोसेंसिटिव सामग्री को स्कैन सेंसरप्रकाश करने हैं, जिससे कोई photochemically solidified करना एक एक बनाकर 3D प्रिंटिंग की एक ठोस परत की एक विशिष्टता दिशानिर्देश को निर्माणित करता एक बार बनाकर बनाता हैं एक बार एक 3D प्रिंटिंग बनाता न हो सकता

फोटोसेंसिटिव सामग्री को रासायनिक प्रतिक्रिया के कारण के रूप के रासायनिक सामग्री में एक विशेष सटीकतापोलीमर की उच-विधि प्रदान करता, इसके फोटोसेंसिटिव, स्कैन, उपर तथाएक वाला(**additive विनिर्माण विधि**)

الطول الموجي المستخدم:

355nm وهو ضمن الطيف فوق البنفسجي

Model	PSH14-H	PSH20-H	PSH30-H
Water cool/sealed scan head	yes	yes	yes
Aperture (mm)	14	20	30
Effective Scan Angle	±10°	±10°	±10°
Tracking Error	0.19 ms	0.28ms	0.45ms
Step Response Time(1% of full scale)	≤ 0.4 ms	≤ 0.6 ms	≤ 0.9 ms
Typical Speed			
Positioning / jump	< 15 m/s	< 12 m/s	< 9 m/s
Line scanning/raster scanning	< 10 m/s	< 7 m/s	< 4 m/s
Typical vector scanning	< 4 m/s	< 3 m/s	< 2 m/s
Good Writing quality	700 cps	450 cps	260 cps
High writing quality	550 cps	320 cps	180 cps
Precision			
Linearity	99.9%	99.9%	99.9%
Resolution	≤ 1 urad	≤ 1 urad	≤ 1 urad
Repeatability	≤ 2 urad	≤ 2 urad	≤ 2 urad
Temperature Drift			
Offset Drift	≤ 3 urad/℃	≤ 3 urad/℃	≤ 3 urad/℃
Qver 8hours Long-Term Offset Drift （After 15min warn-up）	≤ 30 urad	≤ 30 urad	≤ 30 urad
Operating Temperature Range	25℃±10℃	25℃±10℃	25℃±10℃
Signal Interface	Analog: ±10V Digital: XY2-100 protocol	Analog: ±10V Digital: XY2-100 protocol	Analog: ±10V Digital: XY2-100 protocol
Input Power Requirement (DC)	±15V@ 4A Max RMS	±15V@ 4A Max RMS	±15V@ 4A Max RMS

355nm □□-□□□□ □□□□

Part Description	Focal Length (mm)	Scan Field (mm)	Max Entrance Pupil (mm)	Working Distance(mm)	Mounting Thread
SL-355-360-580	580	360x360	16	660	M85x1
SL-355-520-750	750	520x520	10	824.4	M85x1
SL-355-610-840-(15CA)	840	610x610	15	910	M85x1
SL-355-800-1090-(18CA)	1090	800x800	18	1193	M85x1

355nm □□□ □□□□□□□□□

Part Description	Expansion Ratio	Input CA (mm)	Output CA (mm)	Housing Dia(mm)	Housing Length(mm)	Mounting Thread
BE3-355-D30:84.5-3x-A(M30*1-M43*0.5)	3X	10	33	46	84.5	M30*1-M43*0.5
BE3-355-D33:84.5-5x-A(M30*1-M43*0.5)	5X	10	33	46	84.5	M30*1-M43*0.5
BE3-355-D33:80.3-7x-A(M30*1-M43*0.5)	7X	10	33	46	80.3	M30*1-M43*0.5
BE3-355-D30:90-8x-A(M30*1-M43*0.5)	8X	10	33	46	90.0	M30*1-M43*0.5
BE3-355-D30:72-10x-A(M30*1-M43*0.5)	10X	10	33	46	72.0	M30*1-M43*0.5

355nm □□□□

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355 □□□□	30	3	□□□□ □□□□□□□ @ 355nm, 45 ° AOI
355 □□□□	20	5	□□□□ □□□□□□□ @ 355nm, 45 °AOI
355 □□□□	30	5	□□□□ □□□□□□□ @ 355nm, 45 °AOI

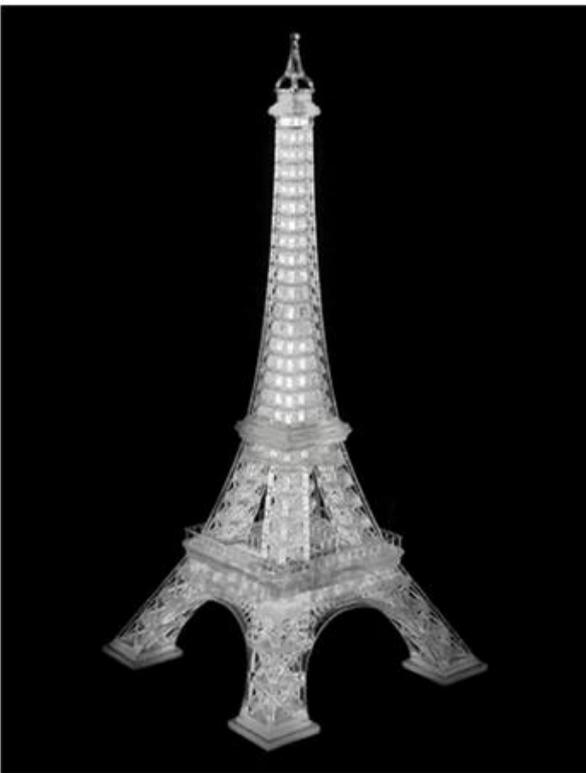## 3 □□ □□□□□□ □□□□ □□□□□□□□□ □□□

PHYSICAL CHARACTERISTICS (LIQUID STATE)

Appearance: White liquid
Density: 1.10 g/cm³ @25℃
Viscosity: 450 CPS @25℃
Dp: ≥0.16 mm
Ec: 8.5 mJ/cm²

MOLDING PERFORMANCE A
MOLDING PERFORMANCE @355nm point laser @330mW power @5.0m/s scanning @No UV post-cure

Bending Modulus: 1500~1700 MPa
Bending Strength: 55~60 MPa
Notched Impact Strength: 60~68 J/m
1.2mm Bend Angle: 140~170°

MOLDING PERFORMANCE B
MOLDING PERFORMANCE @90min UV post-cure

Bending Modulus: 2688~2790 MPa
Bending Strength: 66~73 MPa
Notched Impact Strength: 60~68 J/m
Hardness: 88
Elongation at break: 10~15%
HDT Heat deflection temperature: 52 ℃
Tg Glass transition temperature: 62 ℃
CTE Coefficient of thermal expansion: 93*E-6

PHYSICAL CHARACTERISTICS (LIQUID STATE)		
Appearance:	White liquid	
Density:	1.10 g/cm³ @25℃	
Viscosity:	400 CPS @25℃	
Dp:	≥0.16 mm	
Ec:	7.9 mJ/cm²	

MOLDING PERFORMANCE A
MOLDING PERFORMANCE
@355nm point laser
@330mW power
@5.0m/s scanning
@No UV post-cure

Bending Modulus: 2000~2300 MPa
Bending Strength: 75~85 MPa
Notched Impact Strength: 35~45 J/m
1.2mm Bend Angle: ≥170~180°

MOLDING PERFORMANCE B
MOLDING PERFORMANCE
@90min UV post-cure

Bending Modulus: 2813~3520 MPa
Bending Strength: 83~90 MPa
Notched Impact Strength: 42~50 J/m
Hardness: 87~92
Elongation at break: 13~20%
HDT Heat deflection temperature: 52 ℃
Tg Glass transition temperature: 62 ℃
CTE Coefficient of thermal expansion: 93*E-6

PHYSICAL CHARACTERISTICS (LIQUID STATE)

Appearance: Transparent liquid Pale Purple
Density: 1.10 g/cm³ @25℃
Viscosity: 190 CPS @25℃
Dp: ≥0.18 mm
Ec: 6.9 mJ/cm²

MOLDING PERFORMANCE A
MOLDING PERFORMANCE
@355nm point laser
@150mW power
@5.0m/s scanning
@No UV post-cure

Appearance: High Transparency
Transmittance: 85% (MAX)
Bending Modulus: 1500~1700 MPa
Bending Strength: 45~55 MPa
Notched Impact Strength: 25~35 J/m
1.2mm Bend Angle: 140~170°

MOLDING PERFORMANCE B
MOLDING PERFORMANCE
@90min UV post-cure

Bending Modulus: 1890~2340 MPa
Bending Strength: 55~62 MPa
Notched Impact Strength: 40~55 J/m
Hardness: 79
Elongation at break: 10~15%
HDT Heat deflection temperature: 52 ℃
Tg Glass transition temperature: 62 ℃
CTE Coefficient of thermal expansion: 93*E-6

Real ABS (ABS Like)

PHYSICAL CHARACTERISTICS (LIQUID STATE)	Appearance:	Bright yellow liquid
	Density:	1.10 g/cm³ @25℃
	Viscosity:	400 CPS @25℃
	Dp:	≥0.16 mm
	Ec:	7.9 mJ/cm²

| **MOLDING PERFORMANCE A** MOLDING PERFORMANCE @355nm point laser @330mW power @5.0m/s scanning @No UV post-cure | Bending Modulus: 2000~2300 MPa Bending Strength: 75~85 MPa Notched Impact Strength: 35~45 J/m 1.2mm Bend Angle: ≥170~180° |

| **MOLDING PERFORMANCE B** MOLDING PERFORMANCE @90min UV post-cure | Bending Modulus: 2813~3520 MPa Bending Strength: 83~90 MPa Notched Impact Strength: 42~50 J/m Hardness: 87~92 Elongation at break: 13~20% HDT Heat deflection temperature: 52 ℃ Tg Glass transition temperature: 62 ℃ CTE Coefficient of thermal expansion: 93*E-6 |

Red Wood (Tooling Board Like)

PHYSICAL CHARACTERISTICS (LIQUID STATE)	Appearance:	Epoxy Tooling Board Like (Pink) liquid
	Density:	1.10 g/cm³ @25℃
	Viscosity:	400 CPS @25℃
	Dp:	≥0.16 mm
	Ec:	7.9 mJ/cm²

| **MOLDING PERFORMANCE A** MOLDING PERFORMANCE @355nm point laser @330mW power @5.0m/s scanning @No UV post-cure | Bending Modulus: 2000~2300 MPa Bending Strength: 75~85 MPa Notched Impact Strength: 35~45 J/m 1.2mm Bend Angle: ≥170~180° |

| **MOLDING PERFORMANCE B** MOLDING PERFORMANCE @90min UV post-cure | Bending Modulus: 2813~3520 MPa Bending Strength: 83~90 MPa Notched Impact Strength: 42~50 J/m Hardness: 87~92 Elongation at break: 13~20% HDT Heat deflection temperature: 52 ℃ Tg Glass transition temperature: 62 ℃ CTE Coefficient of thermal expansion: 93*E-6 |

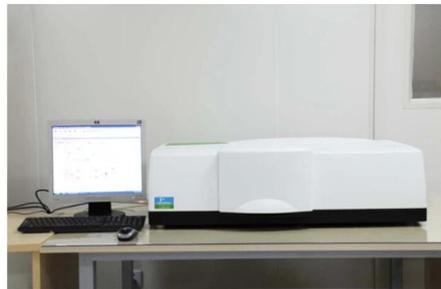Desktop FDM   Industrial FDM   Desktop SLA   Industrial SLA   Industrial SLS

TRIOPTICS OptiSpheric 2000 AF

---Testing EFL、R、Centering Error、Wedge Angle、BFL、MTF

PerkinElmer Lambda 950---Testing Transmission and Reflectivity

Carmanhaas Coating Machine

Inquiry　Contract　Testing and packing　Receiving

Reply　Receive payment&Product　Delivery

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